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**Description and Purpose:**

Addition of ON Semiconductor Gresham, Oregon as wafer fab location (I3T80U technology), currently manufactured in Fab2, Oudenaarde, Belgium and addition of AMKOR P1, Philippines, as an assembly location, (36ld SSOP), currently manufactured in OSPI, Philippines, for NCV78763DQ6R2G. This will increase ON Semiconductor's wafer fab and assembly capacity and flexibility for this device.

For traceability, the dual-source version of the L763DQ6 device will get a new OPN (NCV78763DQ6AR2G) and a fab indicator (F) will be added in the front of the date code where this F will be "2" for Fab2 version and "G" for the Gresham version. Polyimide is also added to the Gresham fab version as part of our global quality continuous improvement program.

**Qualification Plan:**

**Note: Qualification Plan is attached.**

*To access file attachments on pdf copy of PCN, please be guided by the steps below:*

- 1. Download pdf copy of the PCN to your computer*
- 2. Open the downloaded pdf copy of the PCN*
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field*
- 4. Then click on the attached file/s*

Estimated date for qualification completion: **31 August 2016**

**List of Affected Standard Parts:**

Current Part Number	Dual Source Part Number	Qualification Vehicle
NCV78763DQ6R2G	NCV78763DQ6 <u>A</u> R2G	0L763-601 (L763_PBC Gresham)